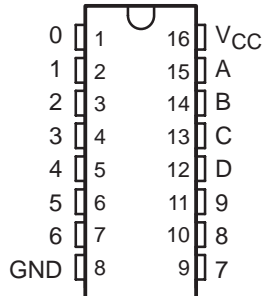


SN54HC42, SN74HC42 4-LINE TO 10-LINE DECODERS (1 of 10)

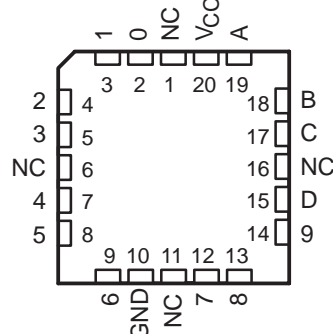
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 14$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Full Decoding of Input Logic
- All Outputs Are High for Invalid BCD Conditions
- Also for Applications as 3-Line to 8-Line Decoders

SN54HC42 . . . J OR W PACKAGE
SN74HC42 . . . D, N, OR NS PACKAGE
(TOP VIEW)



SN54HC42 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These decimal decoders consist of eight inverters and ten 4-input NAND gates. The inverters are connected in pairs to make BCD input data available for decoding by the NAND gates. Full decoding of valid input logic ensures that all inputs remain off for all invalid input conditions.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC42N	SN74HC42N
	SOIC – D	Tube of 40	SN74HC42D	HC42
		Reel of 2500	SN74HC42DR	
		Reel of 250	SN74HC42DT	
–55°C to 125°C	SOP – NS	Reel of 2000	SN74HC42NSR	HC42
	CDIP – J	Tube of 25	SNJ54HC42J	SNJ54HC42J
	CFP – W	Tube of 150	SNJ54HC42W	SNJ54HC42W
	LCCC – FK	Tube of 55	SNJ54HC42FK	SNJ54HC42FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
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SN54HC42, SN74HC42

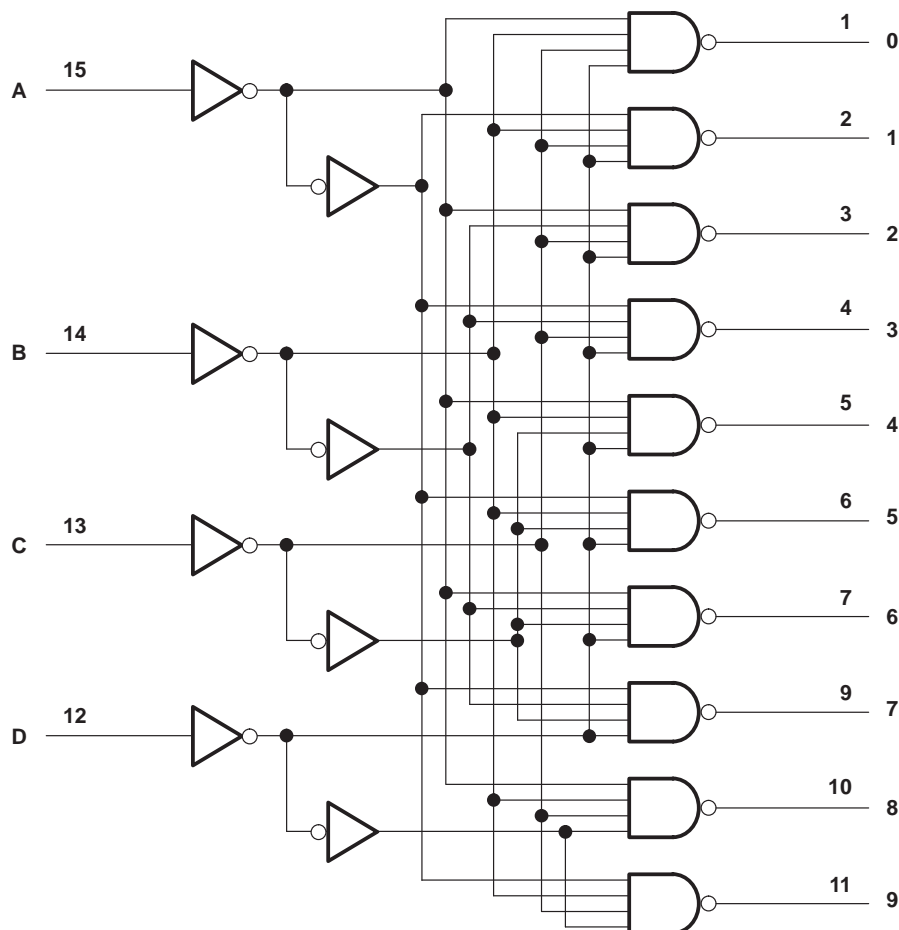
4-LINE TO 10-LINE DECODERS (1 of 10)

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FUNCTION TABLE

NO.	INPUTS				OUTPUTS									
	D	C	B	A	0	1	2	3	4	5	6	7	8	9
0	L	L	L	L	L	H	H	H	H	H	H	H	H	H
1	L	L	L	H	H	L	H	H	H	H	H	H	H	H
2	L	L	H	L	H	H	L	H	H	H	H	H	H	H
3	L	L	H	H	H	H	H	L	H	H	H	H	H	H
4	L	H	L	L	H	H	H	H	L	H	H	H	H	H
5	L	H	L	H	H	H	H	H	H	L	H	H	H	H
6	L	H	H	L	H	H	H	H	H	H	L	H	H	H
7	L	H	H	H	H	H	H	H	H	H	H	L	H	H
8	H	L	L	L	H	H	H	H	H	H	H	H	L	H
9	H	L	L	H	H	H	H	H	H	H	H	H	H	L
Invalid	H	L	H	L	H	H	H	H	H	H	H	H	H	H
	H	L	H	H	H	H	H	H	H	H	H	H	H	H
	H	H	L	L	H	H	H	H	H	H	H	H	H	H
	H	H	L	H	H	H	H	H	H	H	H	H	H	H
	H	H	H	L	H	H	H	H	H	H	H	H	H	H
	H	H	H	H	H	H	H	H	H	H	H	H	H	H

logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
N package	67°C/W
NS package	64°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54HC42, SN74HC42

4-LINE TO 10-LINE DECODERS (1 of 10)

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recommended operating conditions (see Note 3)

			SN54HC42			SN74HC42			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5			0.5			V
		V _{CC} = 4.5 V	1.35			1.35			
		V _{CC} = 6 V	1.8			1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V	1000			1000			ns
		V _{CC} = 4.5 V	500			500			
		V _{CC} = 6 V	400			400			
T _A	Operating free-air temperature		−55	125		−40	85		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC42		SN74HC42		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20\text{ }\mu\text{A}$	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		$I_{OH} = -4\text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2\text{ mA}$	6 V	5.48	5.8		5.2		5.34		
V_{OL}	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20\text{ }\mu\text{A}$	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		$I_{OL} = 4\text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2\text{ mA}$	6 V		0.15	0.26		0.4		0.33	
I_I	$V_I = V_{CC} \text{ or } 0$		6 V		± 0.1	± 100		± 1000		± 1000	nA
I_{CC}	$V_I = V_{CC} \text{ or } 0, I_O = 0$		6 V			8		160		80	μA
C_i			2 V to 6 V		3	10		10		10	pF

SN54HC42, SN74HC42 4-LINE TO 10-LINE DECODERS (1 of 10)

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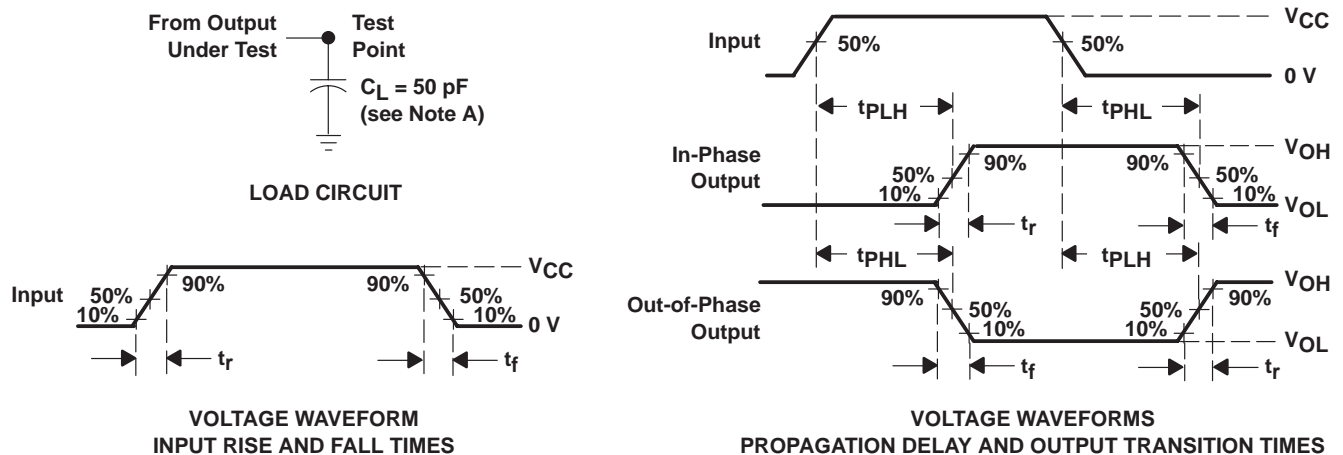
switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC42		SN74HC42		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A, B, C, or D	0–9	2 V		65	150		225		190	ns
			4.5 V		18	30		45		38	
			6 V		14	26		38		32	
t_t		Any	2 V		28	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		7	13		19		16	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	39	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86821012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-86821012A SNJ54HC 42FK	Samples
5962-8682101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8682101EA SNJ54HC42J	Samples
SN54HC42J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC42J	Samples
SN74HC42D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC42	Samples
SN74HC42N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC42N	Samples
SNJ54HC42FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-86821012A SNJ54HC 42FK	Samples
SNJ54HC42J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8682101EA SNJ54HC42J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC42, SN74HC42 :

● Catalog: [SN74HC42](#)

● Military: [SN54HC42](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC42DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC42DR	SOIC	D	16	2500	333.2	345.9	28.6

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

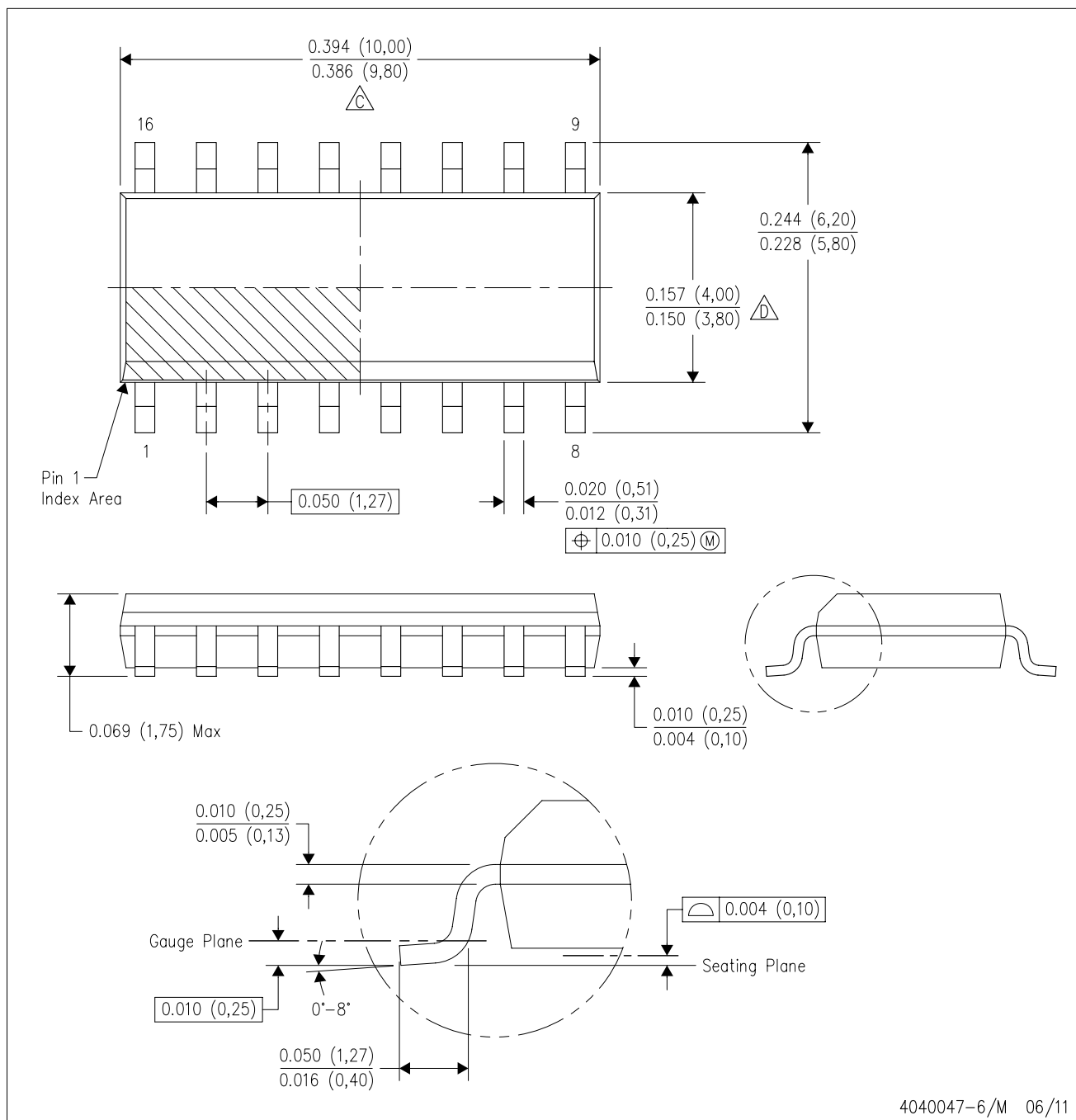


4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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